

DFCH32G14HDHAA

Part Number/Tape & Reel information

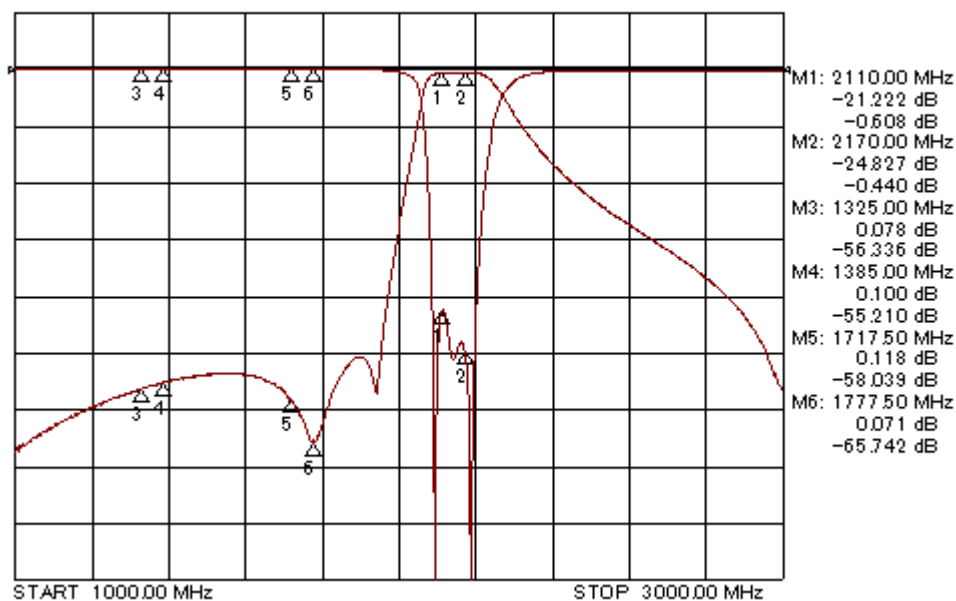
Part Number	Packaging	MOQ
DFCH32G14HDHAA-RF1	330 mm dia. reel	1000 pcs/reel

Specifications -35 to +85°C

Parameter	IN→OUT	
Center Frequency	F0 : 2140.0 MHz	
Band Width (BW)	F0 ± 30.0 MHz	
Insertion Loss	1.3 dB max.	
Ripple at BW	0.6 dB max.	
V.S.W.R. at BW	1.8 max.	
Input Power	1.0 W max.	
Attenuation	1325 ~ 1385MHz	52dB min.
Absolute value	1717.5 ~ 1777.5MHz	52dB min.
Characteristic Impedance	50Ω	

Frequency Response

S11 logMAG 5dB/REF0dB
S21 logMAG 10dB/REF0dB

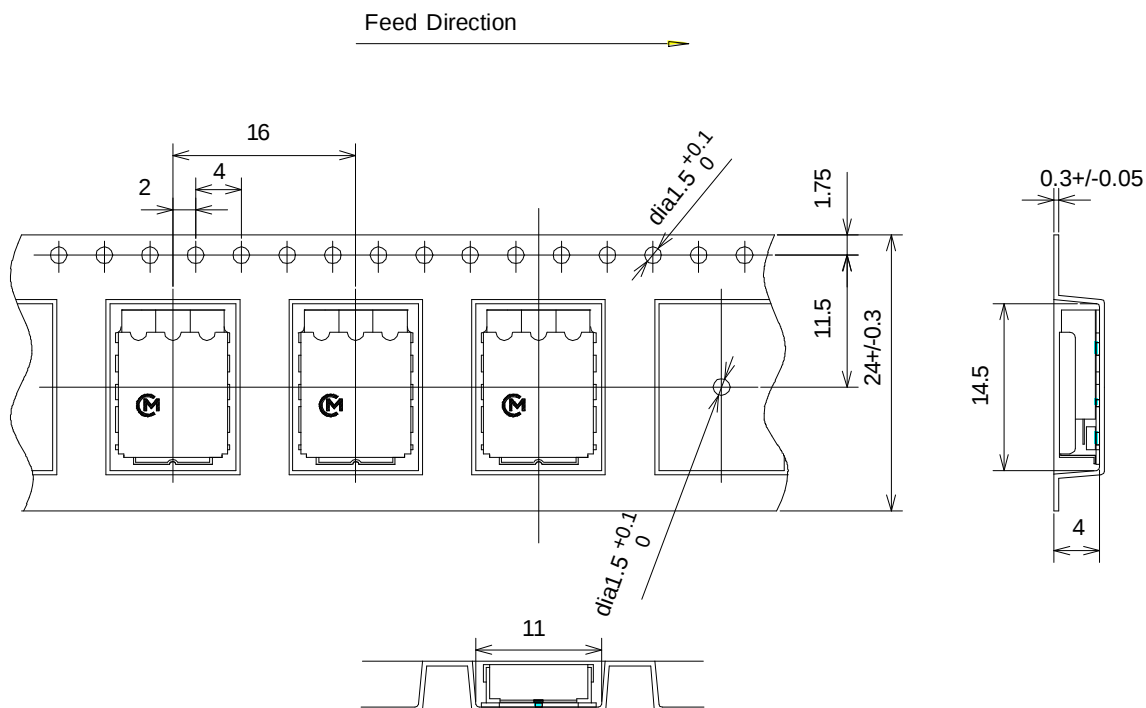


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*Note: All the technical data and information contained herein are subject to change without advanced notice.

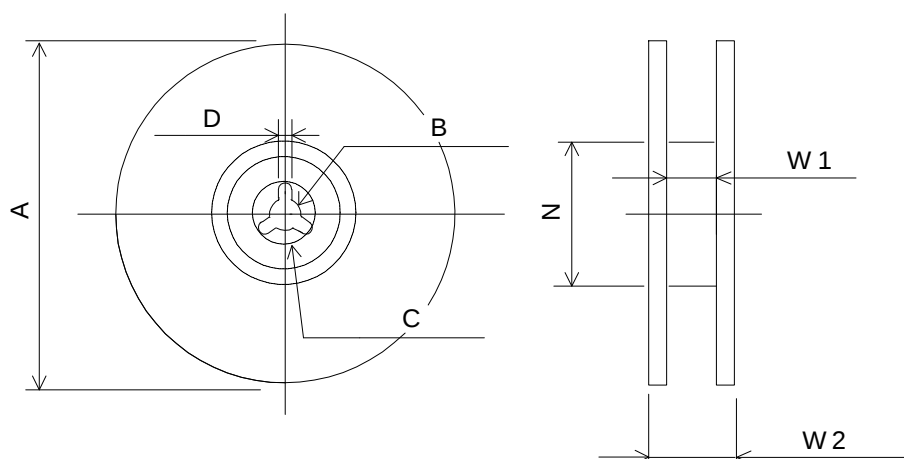
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Dimensions of Carrier Tape



TOLERANCES UNLESS
 OTHERWISE SPECIFIED : ± 0.1
 DIMENSIONS : mm

Dimensions of Reel



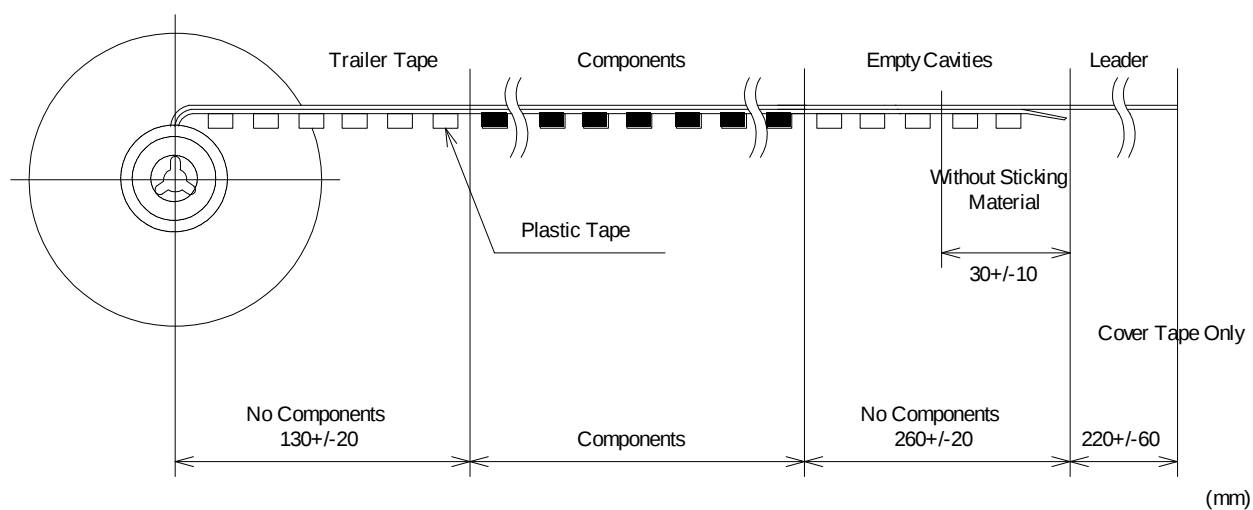
Murata Part Number	A ± 2.0	B ± 0.5	C ± 0.8	D ± 0.5	N (min.)	W1 ± 1.5	W2 (max.)
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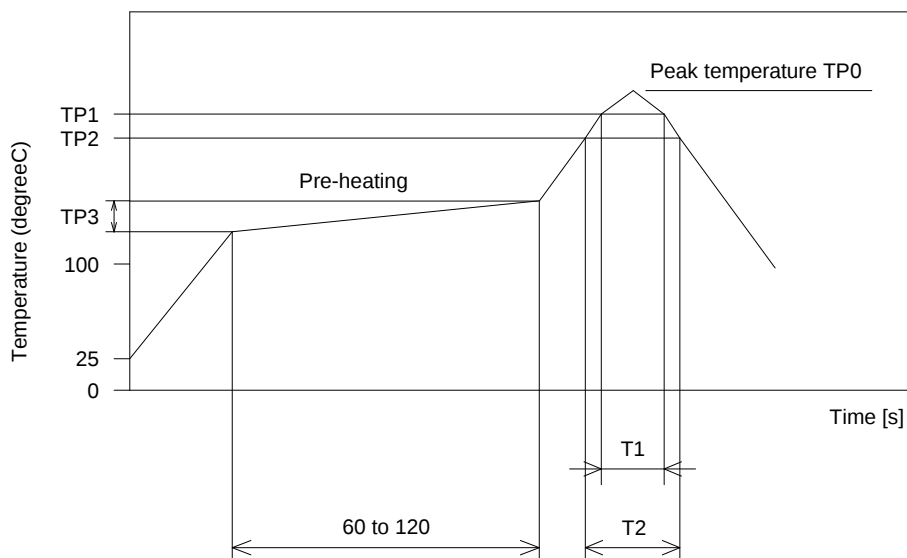
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DFCH32G14HDHAA-RF1	φ 330	φ 13	φ 21	2	φ 50	25.5	31
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Taping Condition

DFCH32G14HDHAA

Reflow Soldering Standard Conditions



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

		TP0 (°C)	TP1 (°C)	T1 (s)	TP2 (°C)	T2 (s)	TP3 (°C)
Reflow standard condition	Sn-40Pb solder	225+/-5	200	20 to 40	---	---	140 to 160
	Sn-3Ag-0.5Cu solder	245+/-5	220	30 to 60	---	---	150 to 180
Test condition of reflow heat resistance		260+5/-0	240	20	220	70	150 to 180

Allowable Temperature and Time of Reflow Soldering

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